

**AMENDMENT TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claims 1 to 9 (Cancelled).

10. (Currently Amended) A micromechanical component, comprising:  
a substrate;  
a micromechanical functional plane provided on the substrate;  
a covering plane provided on the micromechanical functional plane; and  
a printed circuit trace plane provided on the covering plane;  
wherein the covering plane includes a first monocrystalline region epitaxially grown on an underlying second monocrystalline region and a first polycrystalline region epitaxially grown on an underlying first polycrystalline starting layer ~~at the same time~~ side by side.
11. (Previously Presented) The micromechanical component according to claim 10, wherein the micromechanical functional plane includes the second monocrystalline region epitaxially grown on an underlying third monocrystalline region and a second polycrystalline region epitaxially grown on an underlying second polycrystalline starting layer at the same time.
12. (Previously Presented) The micromechanical component according to claim 10, wherein the micromechanical functional plane includes the second monocrystalline region, the second monocrystalline region including an SOI-type monocrystalline region formed above an insulator layer with the substrate.
13. (Previously Presented) The micromechanical component according to claim 10, wherein the first monocrystalline region of the covering plane includes at least one of at least one integrated circuit element of an evaluation circuit and at least one wiring element.
14. (Previously Presented) The micromechanical component according to claim 10, wherein a second polycrystalline region of the micromechanical functional plane includes a movable sensor structure.
15. (Previously Presented) The micromechanical component according to claim 14, wherein the micromechanical functional plane includes a buried polysilicon layer underneath the movable sensor structure.

16. (Previously Presented) The micromechanical component according to claim 10, wherein the printed circuit trace plane includes at least one flip-chip connection element.

17. (Previously Presented) The micromechanical component according to claim 16, wherein the flip-chip connection element includes a gold bump.

18. (Previously Presented) The micromechanical component according to claim 10, wherein the micromechanical component is configured to be manufactured by silicon-surface micromachining.

19. (Currently Amended) A method for manufacturing a micromechanical component, comprising the steps of:

providing a substrate;

providing a micromechanical functional plane on the substrate;

providing a covering plane on the micromechanical functional plane;

providing a polysilicon starting layer region-wise on the micromechanical functional plane and leaving open region-wise a first monocrystalline region of the micromechanical functional plane;

epitaxially depositing a second monocrystalline region on the first monocrystalline region left open and epitaxially depositing on a polycrystalline region starting layer on the polysilicon starting layer at the same time; and

providing a printed circuit trace plane on the covering plane.